



Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 291619US0PCT		SERIAL NO. 10/581,111	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Hubert MORICEAU, et al.		GROUP	
				FILING DATE May 31, 2006			
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
/S.J.N./	AA	2003/211705	11/13/03	TONG, Qin-Yi et al.			
/S.J.N./	AB	4 983 251	01/08/91	HAISMA, Jan et al.			
	AC	2003/0211705					
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO		
/S.J.N./	AO	2 787 919	06/30/00	FR(with English abstract)		YES	NO
/S.J.N./	AP	2 796 491	01/19/01	FR(equivalent of US 6 821 376)		YES	NO
	AQ						
	AR						
	AS						
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
/S.J.N./	AW	TONG, Q.-Y. et al., "Semiconductor Wafer Bonding, Science and Technology", The Electrochemical Society Series, Wiley-Interscience, John Wiley and Sons, Inc., New York (1999).					
/S.J.N./	AX	MORICEAU, H. et al., "The Bonding Energy Control: An Original Way To Debondable Substrates", Conference of International Electrochemical Society, Paris, June 2003.					
	AY						
	AZ						
Examiner /Seahvosh Nikmanesh/					<input type="checkbox"/> Additional References sheet(s) attached Date Considered 02/13/2008		

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.